

FEATURES

- Full E-band coverage, 71 – 86 GHz
- Output power, 7 dBm typ.
- Harmonic isolation, 10 dBc typ.

DESCRIPTION

The gXSB0015 GaAs pHEMT MMIC is an efficient X6 E-band multiplier ideal for point to point radio applications. The chip has an integrated output buffer. At the recommended drive level of 10 dBm the output power is typically 7 dBm with better than 10 dBc harmonic isolation and 300 mW power dissipation.

TYPICAL APPLICATIONS

- E-band point-to-point radio
- Active imaging and sensors
- Automotive radar
- Test instrumentation

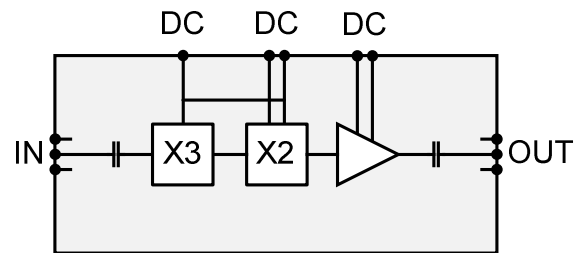


Figure 1. Circuit functional diagram.

ELECTRICAL PERFORMANCE

Table 1. Electrical performance $T_A=25\text{C}$

Parameter	Min	Typ	Max	Unit
Output frequency	71		86	GHz
Input frequency	11.8		14.4	GHz
Multiplication factor		6		
Output power	5	7		dBm
Output power flatness		5		dBpp
Recommended input drive power		10		dBm
Harmonic isolation (relative to X6 output)		10		dBc
Output return loss	10			dB
Input return loss	5			dB
Power dissipation (signal off)		235		mW
Power dissipation (signal on)	250	300	350	mW

MEASURED PERFORMANCE

Measurements have been performed on-wafer at room temperature with typical bias settings and an input drive power if not specified otherwise.

Table 2. Test conditions

Parameter	Setting
Input drive power	10 dBm
Temperature	25°C

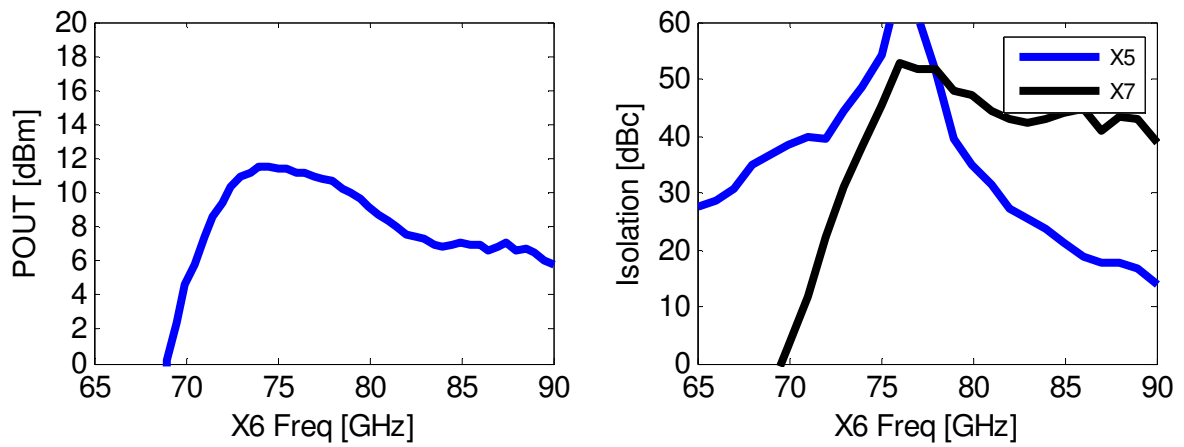


Figure 2. Output power vs X6 output frequency (left). Harmonic isolation vs X6 output frequency (right).

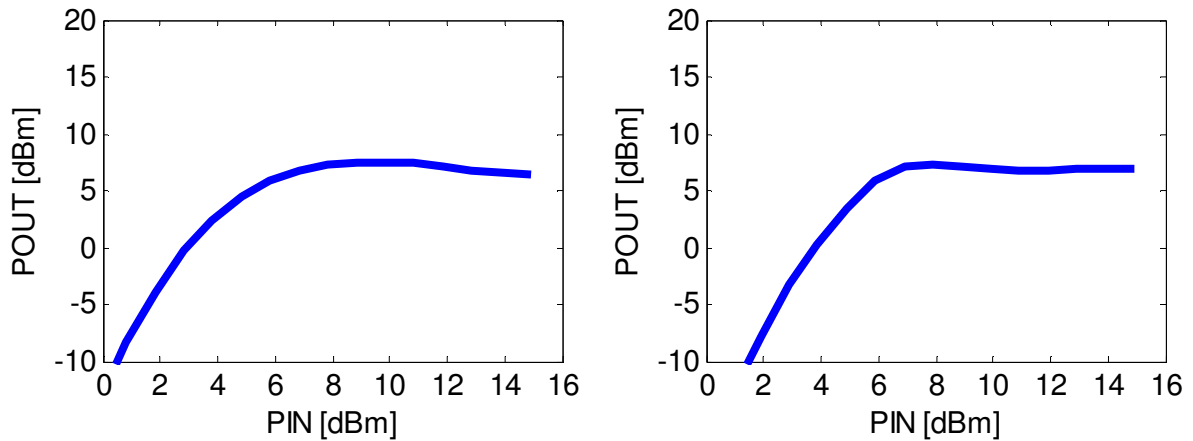


Figure 3. Output power vs input power at 71 GHz (left). Output power vs input power at 86 GHz (right).

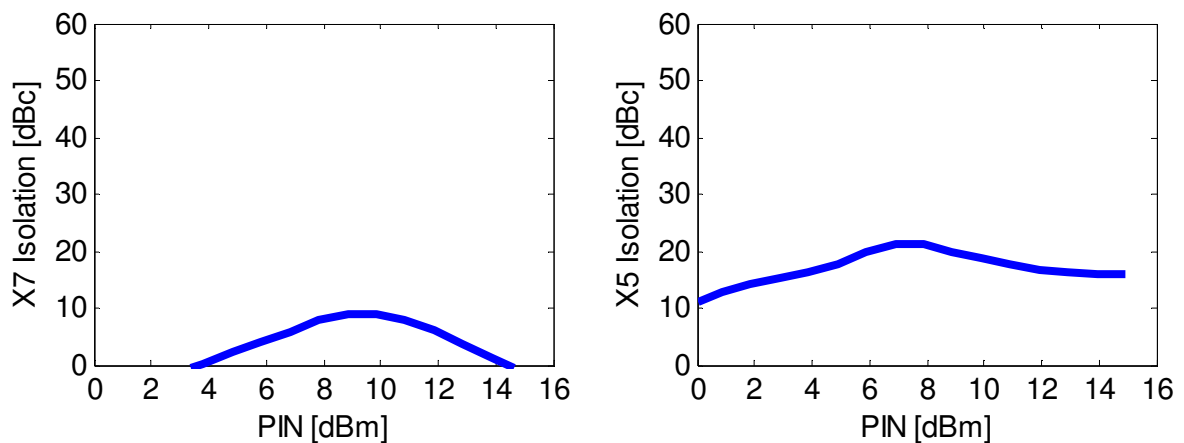


Figure 4. X7 isolation vs input power at 71 GHz (left). X5 isolation vs input power at 86 GHz (right).

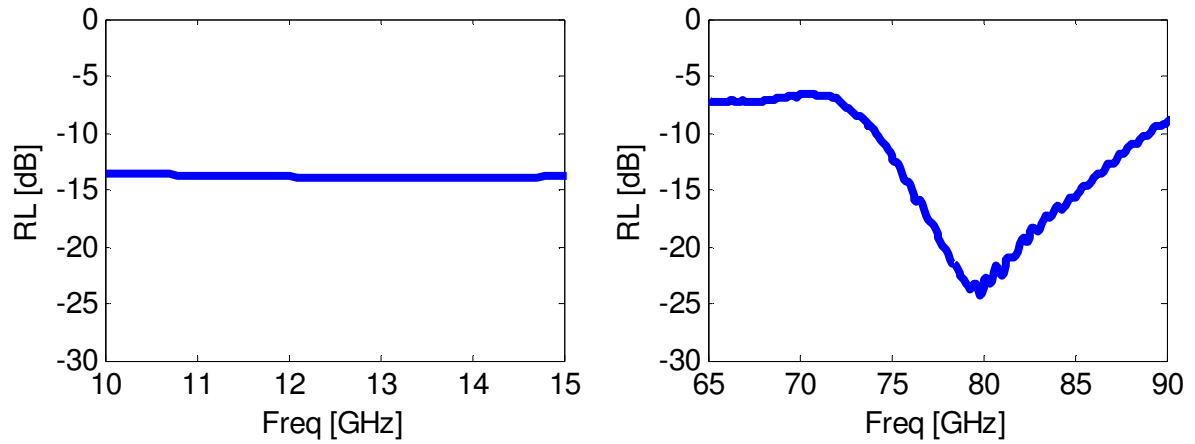


Figure 5. Input return loss (left). Output return loss (right).

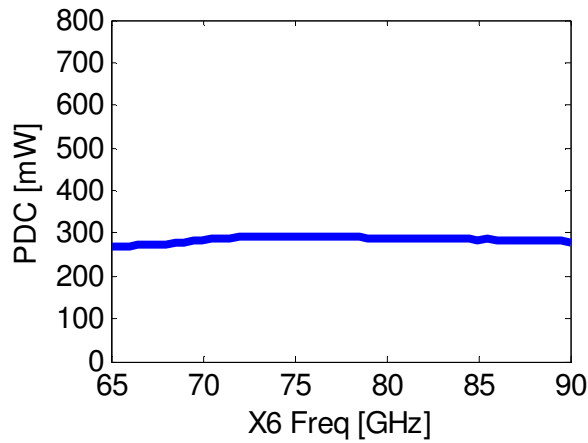


Figure 6. Power dissipation vs X6 output frequency.

RECOMMENDED OPERATING CONDITIONS

Apply the gate (VG_...) supplies first followed by the drain (VD_...) supplies. Gate voltages are adjusted within the typical min/max range to obtain the specified drain currents. The drain currents are stated with all input signals off.

Table 3. Electrical settings, P1 pads

Connector P1	Pad No.	Bias settings (V / mA)			Function
		Min	Typ	Max	
VG_X3	1	-0.6	-0.4	-0.2	Input
VG_X2	2	-1.0	-0.8	-0.6	Input
VD_X	3	3.2	3.3 / 31 ⁽¹⁾	3.4	Input
GND	4				Ground
NC	5				NC
VG_AMP	6	-0.45	-0.25	-0.05	Input
VD_AMP	7	3.2	3.3 / 40	3.4	Input

Table 4. Electrical settings, P2 pads

Connector P2	Pad No.	Settings	Function
GND	1		Ground
RF_OUT	2	50 Ohm, open-circuit at DC	Output
GND	3		Ground

Table 5. Electrical settings, P3 pads

Connector P3	Pad No.	Settings	Function
GND	1		Ground
RF_IN	2	50 Ohm, open-circuit at DC	Input
GND	3		Ground

¹ Adjust VG_X3 at 25 mA and VG_X2 at 6 mA, total current 31 mA.

ABSOLUTE MAXIMUM RATINGS

Table 6. Absolute Maximum Ratings

Gate supply voltage	-2 to + 0.7 V
Drain supply voltage	4.5 V
Gate-drain breakdown	8 V
ID_X	60 mA
ID_AMP	80 mA
Input level	+ 15 dBm
Operating temperature	-40 to + 85 C
Storage temperature	-65 to +150 C

OUTLINE DRAWING

Dimensions are in μm . Substrate thickness is $50 \mu\text{m}$ (GaAs). Drawing is also available in dxf-file format on the web.

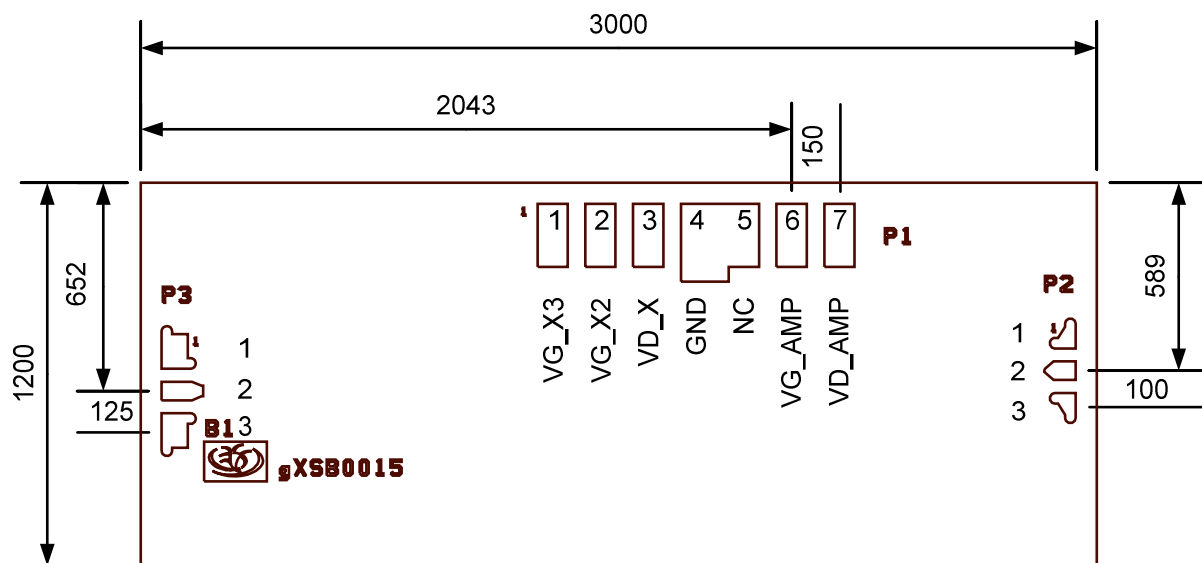


Figure 7. Outline drawing, dimensions are in μm .